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SPECIFICATION AND AND CS63EB2C

PACKAGE OUTLINES Cathode mark 0.20±0.05 -Cathode side Pin1 Pin1 LED Die Pin1 Pin2 Polarity Pin2 0.20±0.05 Cathode side 0.80 0.14 Pin2 Pin1 Polarity LED Die -Pln2 Pin2 Pin2

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CS63EB2C	InGaN	Blue	Water Clear	120°





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit
Forward Current	lF	20	mA
Reverse Current @ 5V	lR	10	μΑ
Power Dissipation	Pd	78	mW
Operating Temperature Range	Тор	-40~+85	°C
Storage Temperature Range	Тѕтс	-40~+100	°C
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	30	mA
Soldering Temperature	TsoL	Max 260°C for	10 sec Max

OPTICAL-ELECTRICAL CHARACTERISTICS

 $(TA=25^{\circ}C)$

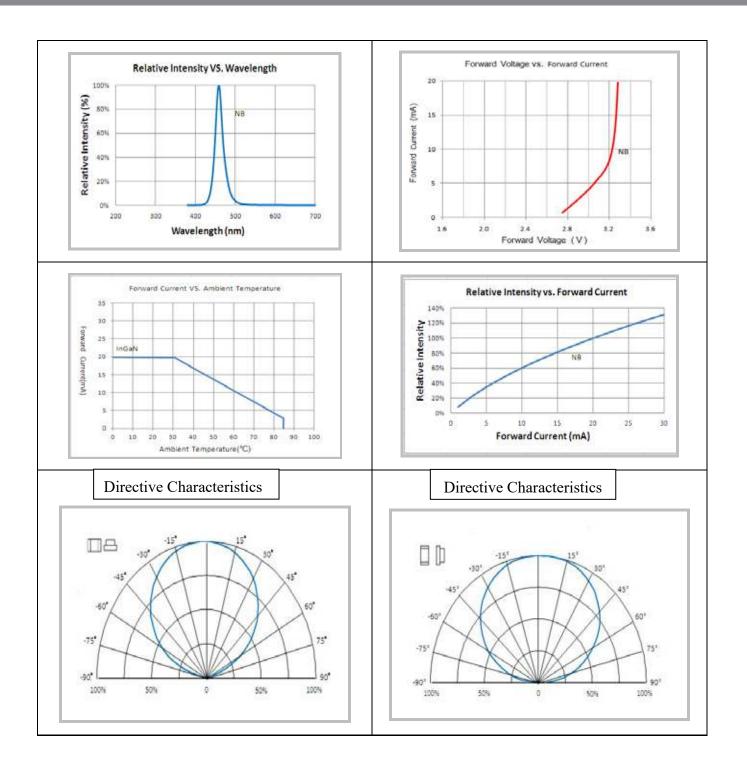
Darameter	Symbol	Test Condition	Value			Llait
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	-	100	-	mcd
Forward Voltage	VF	IF = 20mA	-	3.3	39	V
Reverse Leakage Current	lR	VR = 5V	-	10	-	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	-	120	-	Deg
Peak Wavelength	λР	IF = 20mA	-	468	_	nm
Dominant Wavelength	λD	IF = 20mA	-	470	-	nm

^{*}Tolerance of viewing angle: -10 / +5 deg.





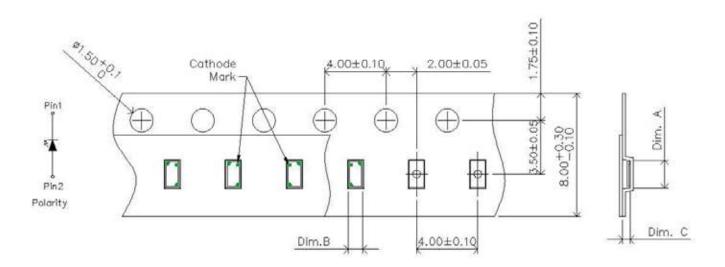
OPTICAL CHARACTERISTIC CURVES



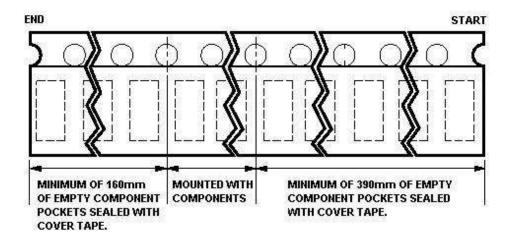




PACKAGING SPECIFICATION



Dim. A	Dim. B	Dim. C	Q'ty/Reel
1.77±0.05	0.97±0.05	0.51±0.05	3K







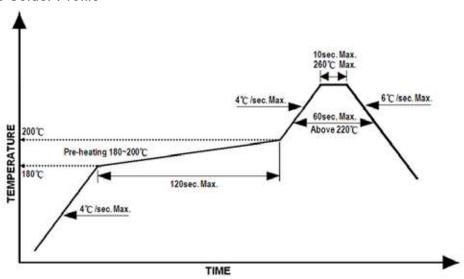
SOLDERING CONDITIONS

Reflow Soldering

Recommend soldering paste specifications:

- 1. Operating temp.: Above 220 ℃ ,60 sec.
- 2. Peak temp.:260°C Max.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never attempt next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



Reworking

- Rework should be completed within 5 seconds under 260℃.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100℃ max, <3min

